Product Change Notification: MFOL-06BQEP127

Date:

21-Feb-2025

Product Category:

Memory

Notification Subject:

CCB 7421 Final Notice: Qualification of CuPdAu as a new wire material, QMI-519 and AMK-EP27 as a new die attach material and AMK-MC27 as a new mold compound for selected 24AA32Ax, 24AA64x, 24FC64x, 24LC32Ax, 24LC64x, AT24C32x, and AT24C64x device families available in 8L SOIC (3.90mm) package.

Affected CPNs:

MFOL-06BQEP127_Affected_CPN_02212025.pdf
MFOL-06BQEP127_Affected_CPN_02212025.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of CuPdAu as a new wire material, QMI-519 and AMK-EP27 as a new die attach material and AMK-MC27 as a new mold compound for selected 24AA32Ax, 24AA64x, 24FC64x, 24LC32Ax, 24LC64x, AT24C32x, and AT24C64x device families available in 8L SOIC (3.90mm) package.

Pre and Post Summary Changes:

	Pre Change			**Post Change**		
Assembly Site	Amkor Technology Philippine	ATX Semiconductor (Shanghai)Co.	Microchip Technology Thailand	Amkor Technology Philippine	ATX Semiconductor (Shanghai)Co.	Microchip Technology Thailand

	(P1/P2), INC. (ANAP)	Ltd (ASSH)	(HQ) (MTAI)	(P1/P2), INC. (ANAP)	Ltd (ASSH)	(HQ) (MTAI)
Device Families	AT24C32x AT24C64x	24AA32Ax 24AA64x 24FC64x 24LC32x 24LC64x AT24C32x AT24C64x	24AA32Ax 24AA64x 24FC64x 24LC32x 24LC64x AT24C32x AT24C64x	AT24C32x AT24C64x	24AA32Ax 24AA64x 24FC64x 24LC32x 24LC64x AT24C32x AT24C64x	24AA32Ax 24AA64x 24FC64x 24LC32x 24LC64x AT24C32x AT24C64x
Wire Material	PdCu	CuPdAu	Au or CuPdAu	CuPdAu	CuPdAu	Au or CuPdAu
Die Attach Material	8290	EN-4900G	8390A	AMK-EP27	EN-4900G	QMI-519
Molding Compound Material	G700A	CEL-9240HF10AK	G600V	AMK-MC27	CEL-9240HF10AK	G600V
Lead-Frame Material	C194	C194	CDA194	C19400FH	C194	CDA194
Lead Plating	NiPdAu	Matte tin	Matte tin	Matte tin	Matte tin	Matte tin
DAP Surface Prep	PPF	Bare Cu	Bare Cu	Bare Cu	Bare Cu	Bare Cu

*Note: C194, A194, CDA194 or C19400FH Lead frame material are the same, it is just a MCHP internal labelling difference.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying CuPdAu as a new wire material, QMI-519 and AMK-EP27 as a new die attach material and AMK-MC27 as a new mold compound.

Change Implementation Status: In Progress

Estimated First Ship Date: 31 March 2025 (date code: 2514)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	February 2025				**March 2025**				
Work Week	06	07	08	09	10	11	12	13	14
Qual Report Availability			X						
Final PCN Issue Date			X						
Estimated Implementation Date									X

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: February 21, 2025: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MFOL-06BQEP127 Qualification Report_ANAP.pdf
PCN_MFOL-06BQEP127 Qualification Report_MTAI.pdf
PCN_MFOL-06BQEP127_Qualification Report_ASSH.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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